12 PIN FLIP-CHIP CSP CASE 499AB-01



ISSUE A

DATE 18 OCT 2004

NOTES:

- NO LES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.550	0.650	
A1	0.215	0.265	
A2	0.36 REF		
D	1.90	2.00	
E	1.4	1.5	
b	0.250	0.350	
е	0.500 BSC		
D1	1.500 BSC		
E1	1.000 BSC		

GENERIC MARKING DIAGRAM*

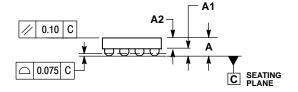


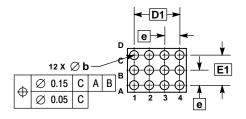
XXXX = Specific Device Code Α = Assembly Location

= Year WW = Work Week G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

4 X D 0.10 C TERMINAL A1 LOCATOR E





DESCRIPTION:	12 PIN FLIP-CHIP CSP	PAGE 1 C	OF 2
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SSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ BY C. GOYAN	05 AUG 2003
Α	CORRECTED MARKING DIAGRAM. REQ. BY T. MANES	18 OCT 2004

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